

## AMENDMENTS TO THE CLAIMS

**Claim 1 (Currently Amended)** A method for manufacturing a flat printed wiring board in which spaces between circuit patterns are filled with a resin, said method comprising the following steps:

laminating via a mold release film a plurality of sets of laminated bodies formed by superposing a semi-cured resin sheet on a printed wiring board with said circuit patterns formed thereon;

\_\_\_\_\_ placing the laminated plural sets of said laminated bodies interposed between a pair of smoothing plates; and

\_\_\_\_\_ collectively pressing said laminated bodies in a reduced pressure atmosphere ~~in order to cure said resin;~~

\_\_\_\_\_ curing said resin; and then

\_\_\_\_\_ polishing said cured resin covering said circuit patterns, thereby exposing said circuit patterns.

**Claim 2 (Currently Amended)** The method for manufacturing the flat a-printed wiring board according to claim 1, wherein said circuit patterns are formed on both sides of said printed wiring board.

**Claim 3 (Currently Amended)** The method for manufacturing the flat a-printed wiring board according to ~~claim 1 or claim 2,~~ including a further step of superposing wherein a metallic foil with a roughened surface facing said resin layer onto ~~is superposed on said resin layer.~~

**Claim 4 (Currently Amended)** The method for manufacturing the flat a-printed wiring board according to claim 3, wherein said metallic foil is formed with a different kind of metal than the kind of metal used to form said circuit pattern.

**Claim 5 (New)** The method for manufacturing the flat printed wiring board according to claim 4, wherein said metallic foil is nickel.

**Claim 6 (New)** The method for manufacturing the flat printed wiring board according to claim 3 wherein the step of polishing comprises the steps of:

ceramic buff polishing to remove resin layers from the circuit pattern; and  
finish polishing to reduce the average roughness of the surface of the flat printed wiring board.

**Claim 7 (New)** The method for manufacturing the flat printed wiring board according to claim 1 wherein said circuit patterns are formed by an additive method.

**Claim 8 (New)** A method for manufacturing a flat printed wiring board in which spaces between circuit patterns are filled with a resin, said method comprising the following steps:

superposing a semi-cured resin sheet on said circuit pattern printed on a printed wiring board to form a board assembly;  
stacking a predetermined number of said board assemblies with a mold release film interposed between every adjacent said board assembly to create a stack of board assemblies;  
superposing a first smoothing plate on a first surface of said stack of board assemblies via a first mold release film;  
superposing a second smoothing plate on a second surface of said stack of board assemblies via a second mold release film;  
pressing said first and second smoothing plates and said stack of board assemblies in a reduced atmosphere environment;  
heating said stack of board assemblies so as to cure the semi-cured resin sheets;  
polishing each board assembly so as to expose each corresponding said circuit pattern.

**Claim 9 (New)** The method for manufacturing the flat printed wiring board according to claim 8, wherein said printed wiring board of said board assembly comprises a first board surface and a second board surface, and

wherein said circuit pattern is printed on said first board surface, and  
wherein a second circuit pattern is printed on said second board surface, and  
wherein a second semi-cured resin sheet is superposed on said second circuit pattern, and

wherein each board assembly is further polished to expose each corresponding second circuit pattern.

**Claim 10 (New)** The method for manufacturing the flat printed wiring board of claim 9 further comprising the steps of:

superposing a metallic foil with a roughened surface onto said semi-cured resin sheet wherein the roughened surface contacts said semi-cured resin sheet, and

superposing a second metallic foil with a second roughened surface onto said second semi-cured resin sheet wherein the second roughened surface contacts said second semi-cured resin sheet.

**Claim 11 (New)** A method for manufacturing a flat printed wiring board comprising the steps of:

stacking a semi-cured resin sheet on each of a surface of a printed wiring board comprising a printed circuit pattern ;

stacking a metallic foil with a roughened surface onto each of the semi-cured resin sheets wherein the roughened surface contacts the corresponding semi-cured resin sheet;

stacking a predetermined number of the printed wiring boards comprising said corresponding semi-cured resin sheets, said corresponding metallic foils, and said corresponding circuit patterns, wherein adjacent printed wiring boards are separated by a corresponding mold release film and additional said corresponding mold release films are also placed over a first end and a second end of said stack of printed wiring boards;

placing said stack of printed wiring boards and said corresponding mold release films between a first smoothing plate and a second smoothing plate;

compressing said first smoothing plate and said second smoothing plate and said corresponding stack of printed wiring boards and said corresponding mold release films in a reduced pressure environment so as to reduce a thickness of each of a combination of printed wiring board and corresponding semi-cured resin sheets;

heating said stack of printed wiring boards so as to cure each said corresponding semi-cured resin sheets;

removing said corresponding metallic foils from each printed wiring board;

polishing each printed wiring board to expose said corresponding circuit patterns.

**Claim 12 (New)** The method for manufacturing the flat printed wiring board of claim 11, wherein said printed circuit pattern comprises:

a first printed circuit pattern printed on a first surface of the printed wiring board; and  
a second printed circuit pattern printed on a second surface of the printed wiring board.

**Claim 13 (New)** The method for manufacturing the flat printed wiring board of claim 12, wherein said first printed circuit pattern and said second printed circuit pattern are respectively formed by a subtractive method.

**Claim 14 (New)** The method for manufacturing the flat printed wiring board of claim 12, wherein a thermosetting epoxy resin is used as a material of said semi-cured resin sheets.

**Claim 15 (New)** The method for manufacturing the flat printed wiring board of claim 12, wherein a thermosetting resin is used as a material of said semi-cured resin sheets.

**Claim 16 (New)** The method for manufacturing the flat printed wiring board according to claim 1, including a further step of superposing a metallic foil with a roughened surface facing said resin layer onto said resin layer.

**Claim 17 (New)** The method for manufacturing the flat printed wiring board according to claim 16, wherein said metallic foil is formed with a different kind of metal than the kind of metal used to form said circuit pattern.